Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

****

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size = .008 x .008”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .013” X .013” DATE: 5/8/23**

**MFG: SILICON SUPPLIES THICKNESS .008” P/N: BZX55A5V6**

**DG 10.1.2**

#### Rev B, 7/1